

KMU396 MATERIAL SCIENCE AND TECHNOLOGY- I

X-ray Photoelectron Spectroscopy (XPS)

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Outline

- History
- What is XPS?
- Instrumentation
- How XPS Works?
- XPS Spectrum
- Advents and disadvantages of XPS
- Summary
- References

History

- XPS technique is based on the photoelectric effect which was discovered by German physicist G. Hertz in 1887.
- Developed around 1905 by Einstein, A. Ann. Phys. Leipzig.
- Kai Siegbahn and his group in Uppsala (Sweden) developed several significant improvements in the equipment.
- In 1954 recorded the first XPS spectrum.
- In 1981, Siegbahn received Nobel Prize in physics.

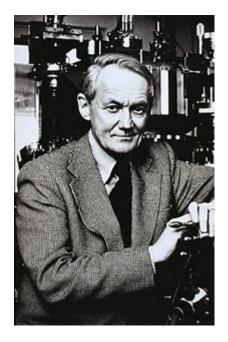


Figure 1: Professor Kai Siegbahn, the founder of x-ray photoelectron

Spectroscopy. Department of Chemistry, Moscow State University, Vorob'evy gory, Moscow, 119999 Russia

Journal of Analytical Chemistry, Vol. 60, No. 3, 2005, pp. 297–300. Translated from Zhurnal Analiticheskoi Khimii, Vol. 60, No. 3, 2005, pp. 331–334.

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What is XPS?

- X-ray photoelectron spectroscopy (XPS) is used for physical methods of surface analysis.
- XPS is a quantitative spectroscopic technique for solids. Some special design XPS instruments can analyze volatile liquids or gases.
- Measures,
- elemental composition
- > empirical formula
- chemical state
- electronic state
 of the elements that exist within a material.

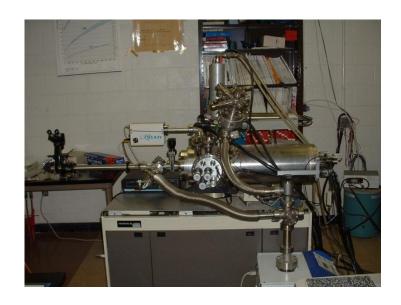


Figure 2: University of Texas at El Paso, Physics Department Side view of the Phi 560 XPS/AES/SIMS UHV System http://www-group.slac.stanford.edu/sms/xrayspectroscopy.html

Ideal Uses for XPS Analysis

- Surface analysis of organic and inorganic materials, stains, or residues
- Determining composition and chemical state information from surfaces (e.g., polymers, glasses)
- Thin film oxide thickness measurements (SiO₂, Al₂O₃ etc.)
- Corrosion
- Adhesion

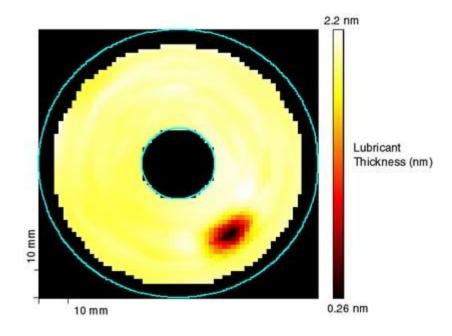


Figure.3. An XPS lubricant thickness map shows the presence of a void in the 2 nm lubricant coating on a 95 mm diameter hard disk media.

http://www.phi.com/surface-analysis-applications/magnetic-media.html

Relevant Industries for XPS Analysis

- Aerospace
- Automotive
- Biomedical/biotechnology
- Compound Semiconductor
- Data Storage Defense
- Displays
- Electronics
- Industrial Products
- Lighting
- Pharmaceutical
- Photonics
- Polymer
- Semiconductor
- Solar Photovoltaics
- Telecommunications



Figure 4: Pharmaceutical Industry http://www.legaljuice.com/2010/12/salesman_calls_the_cops after.html



Figure 5: Solar Photovoltaics http://www.fincher.org/Misc/AlternateEnergy.shtml

Limitations of XPS Analysis

- The smallest analytical area is approximetly 10 nm.
- Limited specific organic information.
- Sample must be compatible with an ultra-high vacuum (UHV) environment (>10-9 Torr).
- Sample size cannot exceed 1 in. (25 mm) in any direction.
- Height should not exceed ½ in. (12 mm).
- Detects all elements with an atomic number of 3 (lithium) and above.

Photoelectric Effect

- Ionization occurs when matter interacts with light of sufficient energy (Heinrich Hertz, 1886)
- Photoelectron spectroscopy is based upon a single photon in/electron out process.

$$E = h v$$

h - Planck constant (6.62 x 10⁻³⁴ J s)

v - frequency (Hz) of the radiation

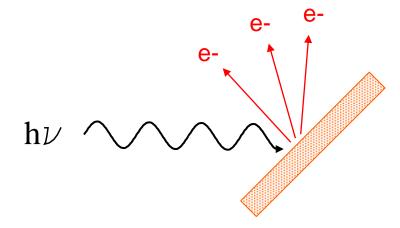


Figure 6: Photoelectron Phenomenon www.pes.arizona.edu/facility/PES%20lecture1-history.pdf

Photoelectron vs Other Spectroscopies

Photoelectron

- Photon just needs enough energy to eject electron
- Measure kinetic energy of ejected electrons
- Monochromatic photon source

Others

- Photon must be in resonance with transition energy
- Measure absorbance or transmittance of photons
- Scan photon energies

Instrumentation

- X-ray source
- Electron energy analyzer
- An ion gun
- Ultrahigh vacuum system <
 10-9 Torr (< 10-7 Pa)
- Electronic controls
- Computer system

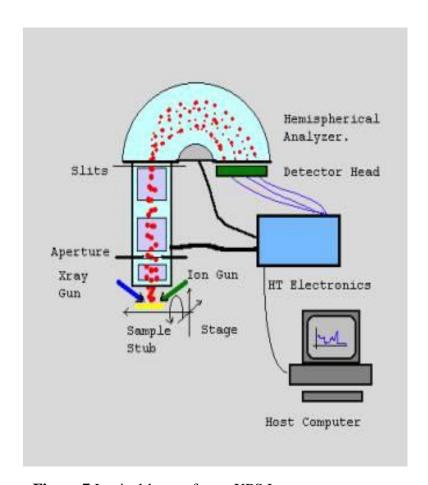


Figure 7:Logical layout for an XPS Instrument. http://www.casaxps.com/help_manual/XPSInformation/XP SInstr.htm

How XPS Works?

- A monoenergetic x-ray beam emits photoelectrons from the surface of the sample.
- UHV environment to eliminate excessive surface contamination
- Electron Energy Analyzer (CHA) measures the KE of emitted e⁻s
- The spectrum plotted by the computer from the analyzer signal
- The binding energies can be determined from the peak positions and the elements present in the sample identified.

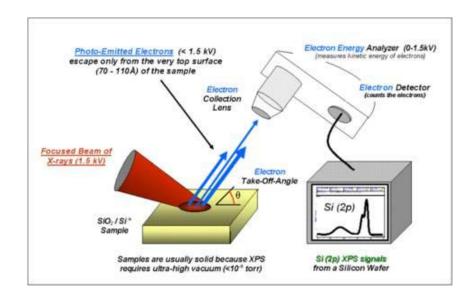


Figure 8: XPS instruments http://wiki.utep.edu/display/~vrrangel/X-ray+Photoelectron+Spectroscopy+%28XPS%29

X-Ray Source

- X-ray hitting the core electrons (e⁻) of the atoms.
- e-s are going to be released giving the Kinetic Energies (KE) characteristic of their elements.
- The most widely used x-ray sources are:
- ✓ monochromatic aluminium Kα X-rays(AlKα)
- \checkmark polychromatic magnesium K α X-rays (MgK α).

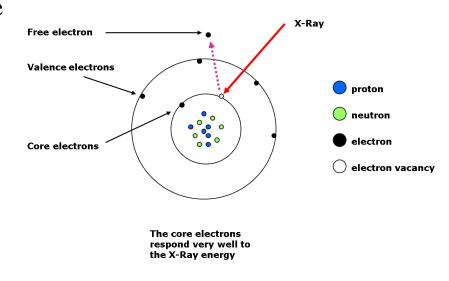
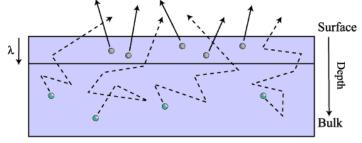


Figure 9: The core electrons respond to X-Ray energy www.casaxps.com/help_manual/XPSInformation/XPSInstr.htm

Binding Energy

- The Binding Energy (BE) is characteristic of the core electrons for each element.
- By measuring the kinetic energy of the emitted electrons, the binding energy can be determined for the photoelectrons detected.

 $E_{h\nu}$ = electron kinetic energy + electron binding energy



- electrons from the near surface region, without energy loss
- electrons from the bulk, with random energy loss

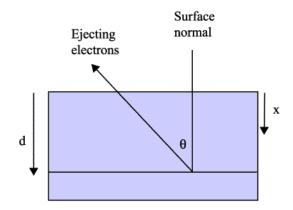


Figure 10: Electrons from the sample surface. http://mee-inc.com/xray-photo.html

Electron Energy Analyzer

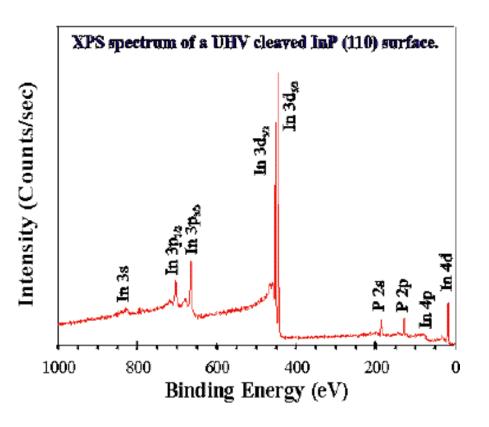
Concentric Hemispherical Analyzer (CHA)

- CHA is based on the deflection of charged particles in an electrostatic field according their KE.
- After passing through an energy selecting field only electrons are detected which have a velocity within a certain kinetic energy region (ΔE).
- For the spectrum the energy region is scanned successively with constant ΔE by continuous change of the deflection potentials.

Why Does XPS Need UHV?

- The pressure of the vacuum system is $\leq 10^{-9}$ Torr
- XPS is a surface sensitive technique
 Contaminates will produce an XPS signal and lead to incorrect analysis of the surface of composition.
- To be analysed without interference from gas phase collisions
- Many vacuum components work with heated filaments and high voltages. Their work free of failure only is warranted under UHV conditions.

XPS Spectrum



• The number of electrons detected vs. the binding energy values.

BE increase from right to left



KE increase from left to right

XPS Spectrum

This spectrum comprises two sets of information:

- 1. The position of the peaks; Binding energy value of the maximum point of the peak.
- 2. The shape of each of the peaks determines the concentration of the chemical elements.

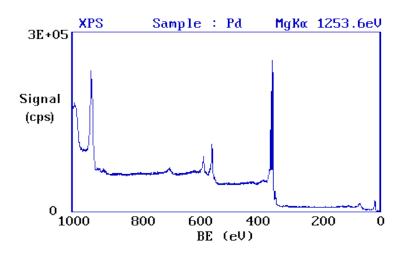


Figure 11: XPS Spectrum of Pd

XPS Spectrum

- There are tables with the KE and BE already assigned to each element.
- The plot has characteristic peaks for each element found in the surface of the sample.
- The intensity of the peaks is related to the concentration.
- The technique provides a quantitative analysis of the surface composition

Advents of XPS

- Chemical state identification on surfaces
- Identification of all elements except for H and He
- Quantitative analysis, including chemical state differences between samples
- Oxide thickness measurements
- Very simple to use and the data is easily analyzed.
- The UHV environment prevents contamination of the surface and aid an accurate analysis of the sample.
- The XPS technique is non-destructive because it produces soft x-rays to induce photoelectron emission from the sample surface

Disadvantages of XPS

- Expensive
- Slow
- Poor spatial resolution
- Requires high vacuum

Summary

- Surface sensitive technique
- Core spectroscopy
- Characterizes solids with a depth 10nm
- Needs UHV environment
- Characteristic binding energy.
- Characteristic set of peaks related KE plotted depending on BE
- The intensity of the peaks is related to the concentration.
- Quantitative technique

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Thank You for Your Attention!

